

Advancements in Quartz Based Oscillator Technologies **rakon**

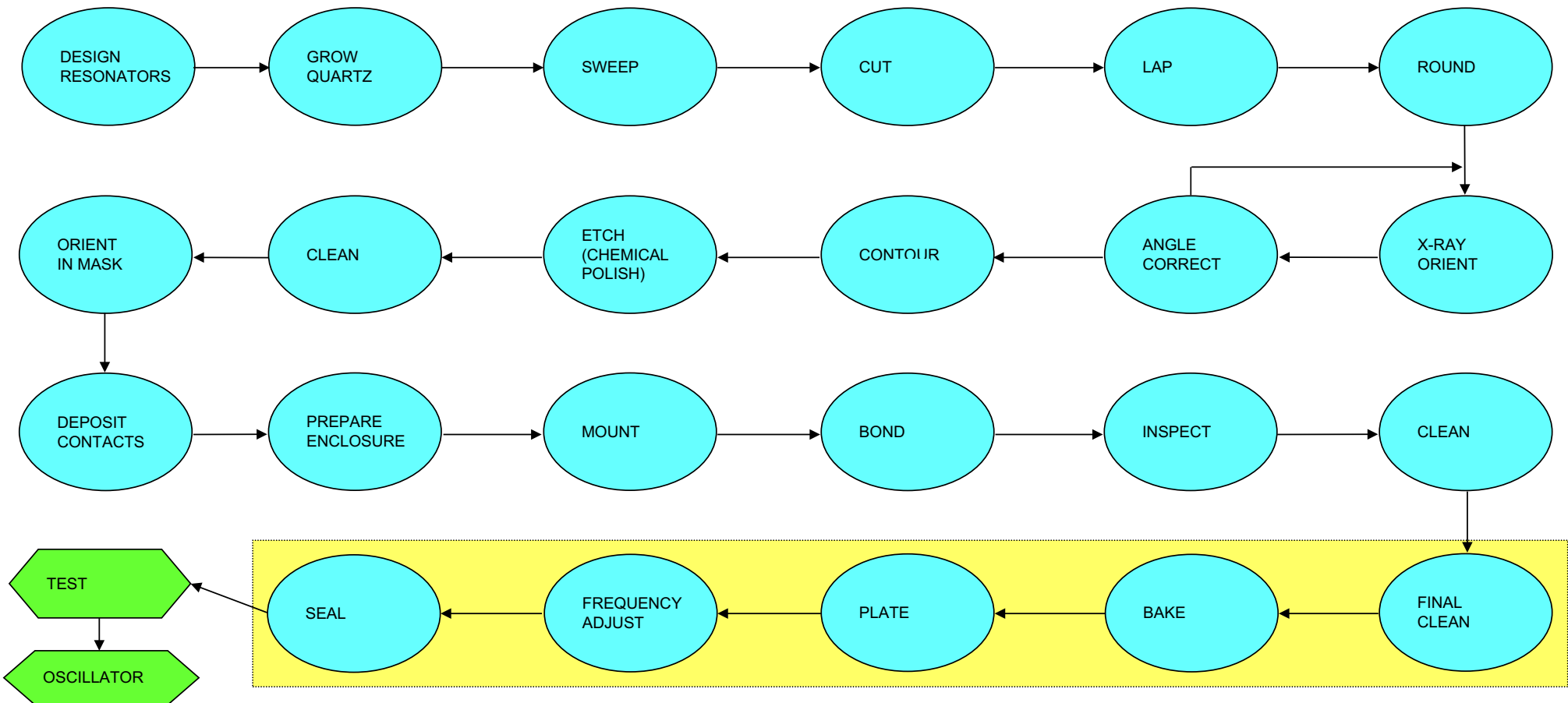
**Advanced Timing for
High Speed Connectivity**

Topics



- ◀ Background
- ◀ Resonator Improvements
- ◀ Profile, Power & Performance
- ◀ Atomic clock stabilities with Quartz

Resonator Fabrication



Low Profile Crystals

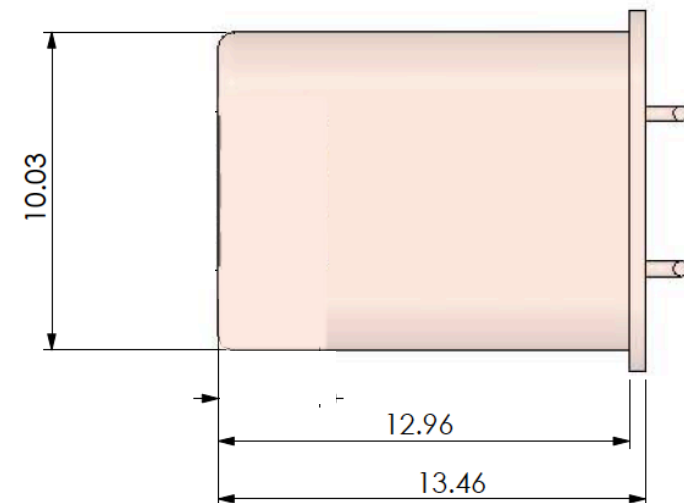
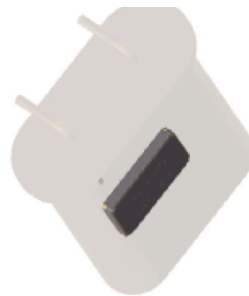
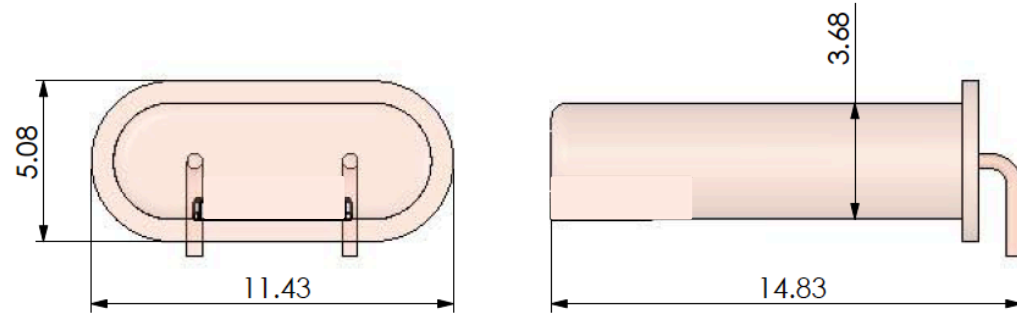
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< SC vs Stripped SC

□ HC43 vs Strip

□ Key Advantages in :

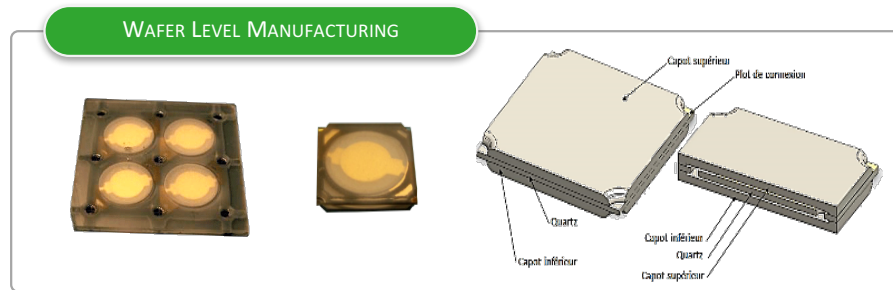
- Size
- Power
- Performance
- Higher reliability
- Automated process
- Low component OCXOs



Low Profile Crystals – 2



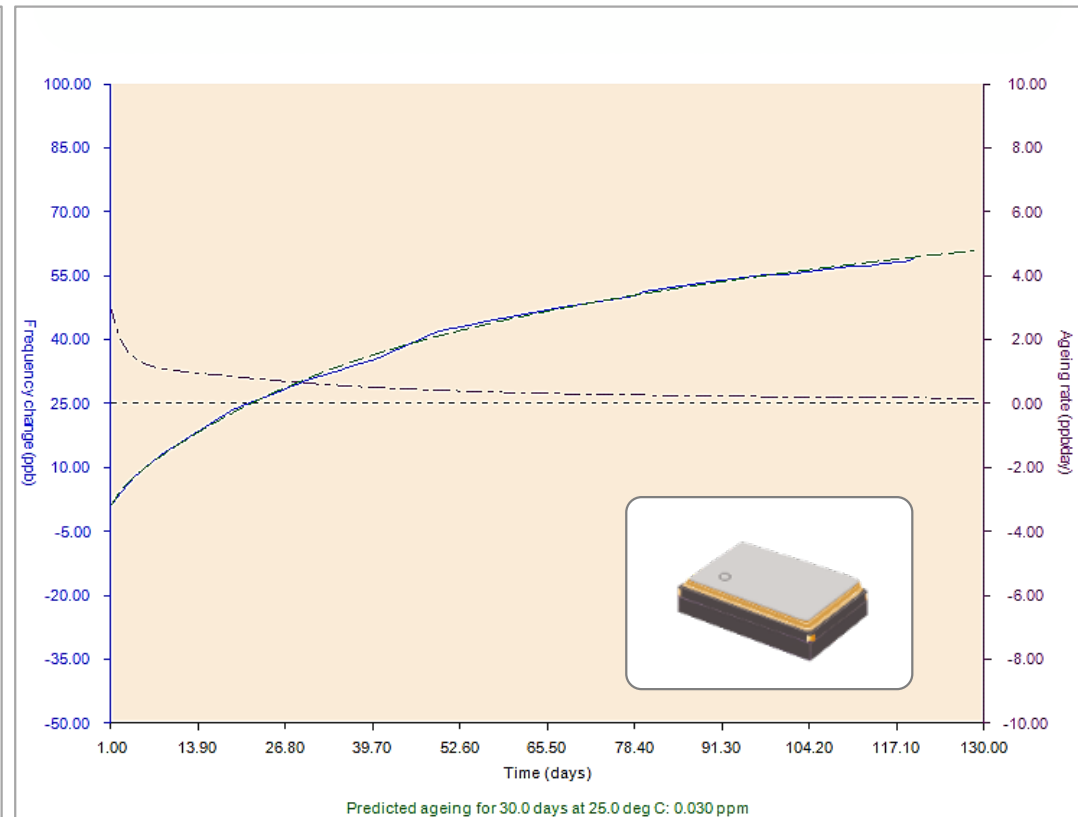
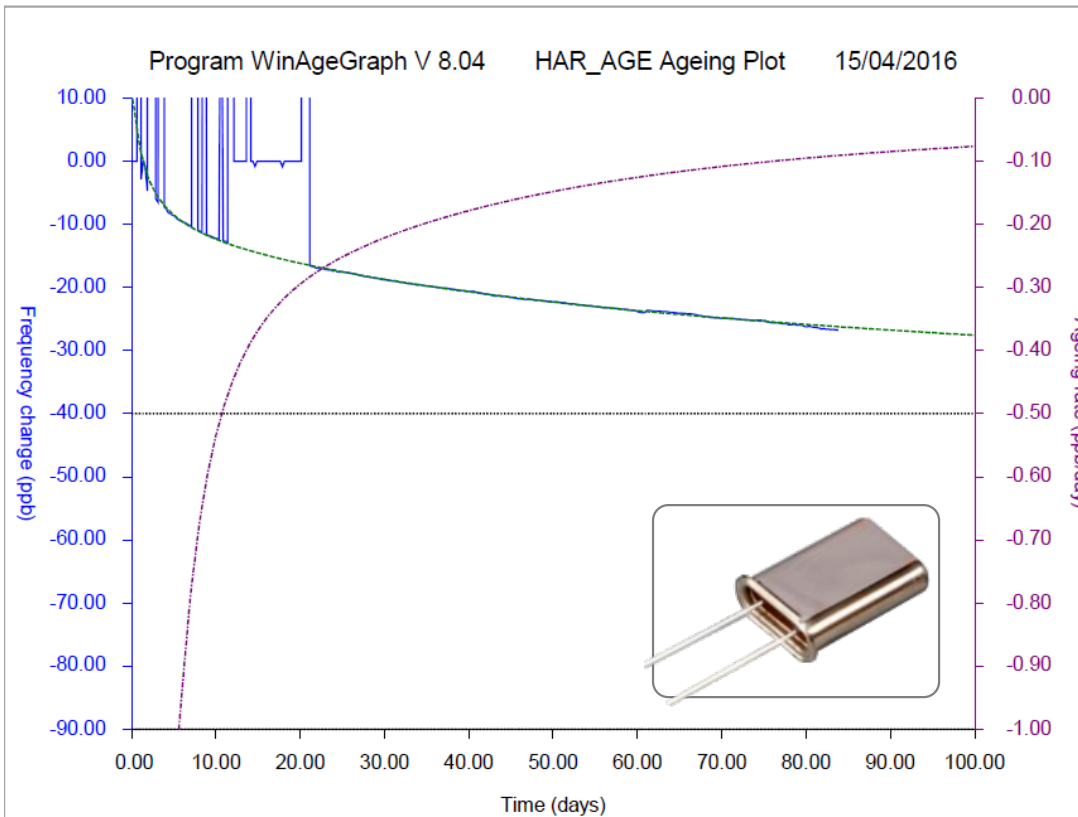
◀ Quartz Crystal ½ Package Size



Low Ageing Crystals

HC-43 30T SC-Cut: <0.5 ppb/day @ 10 days

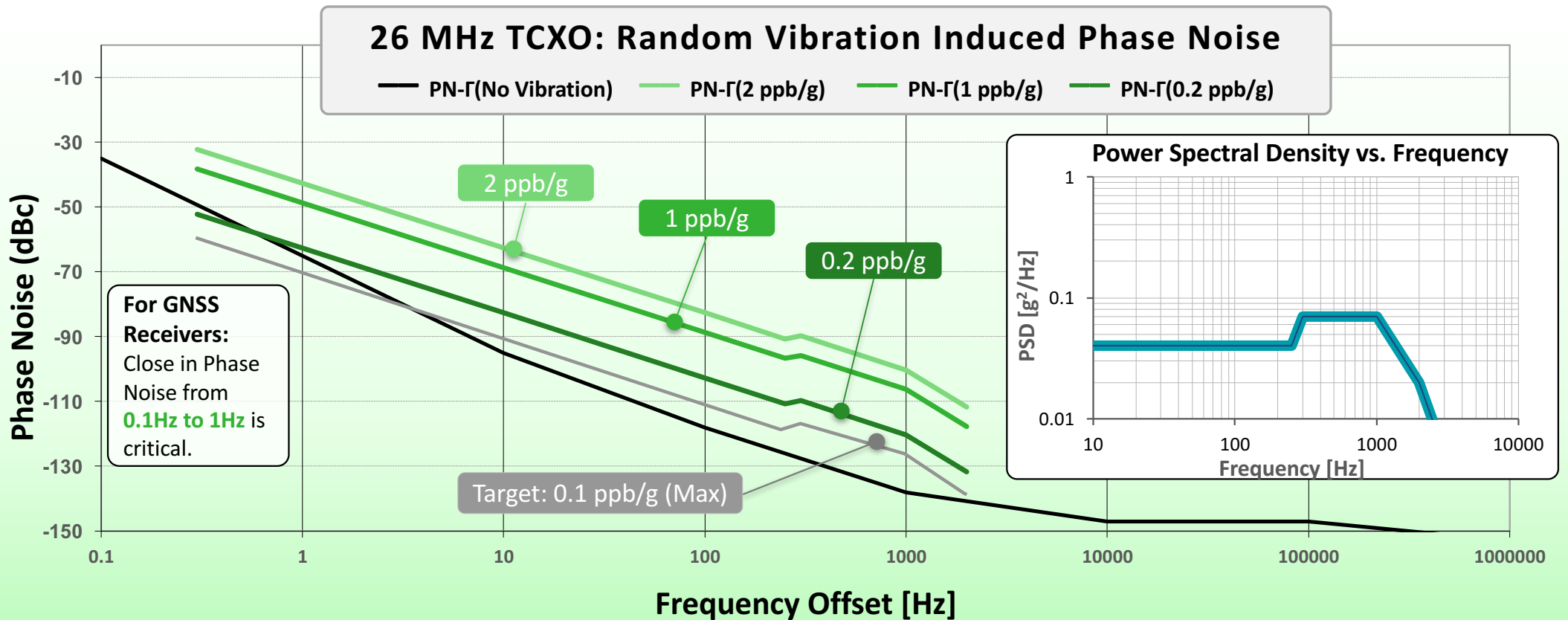
Strip Crystal: <0.5 ppb/day @ ~30 days



Phase Noise vs. *g*-Sensitivity



 In the presence of Vibration, oscillator Phase Noise is degraded. Oscillators with low *g*-sensitivity will reduce the impact of Vibration.

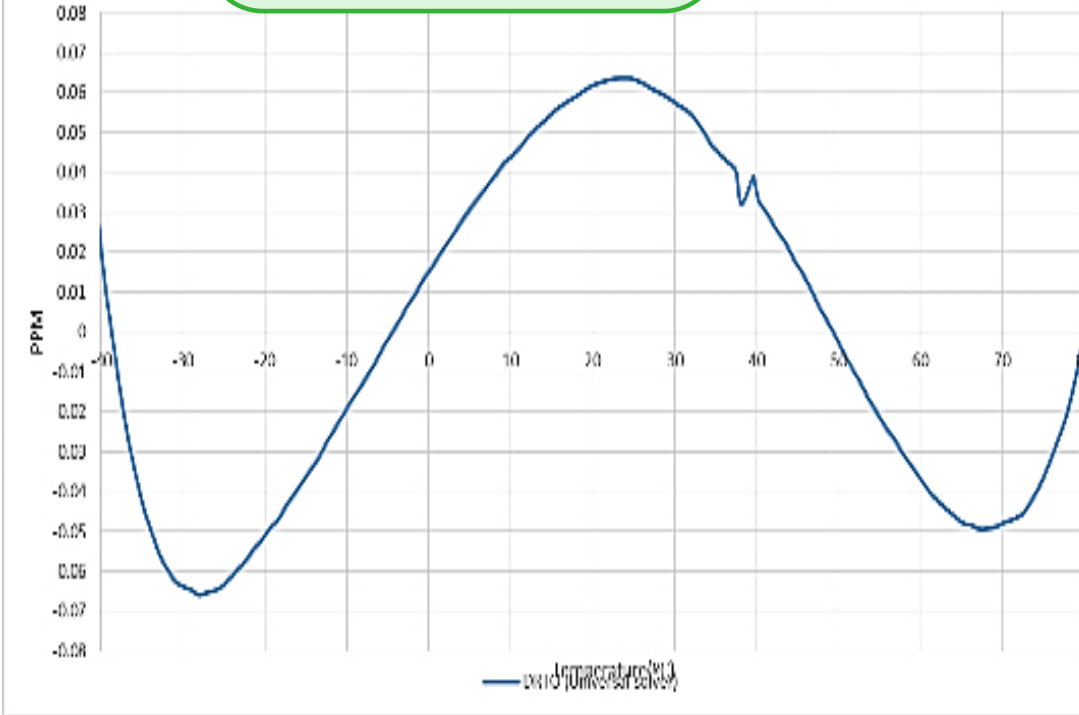


TCXOs with low F vs T & slope

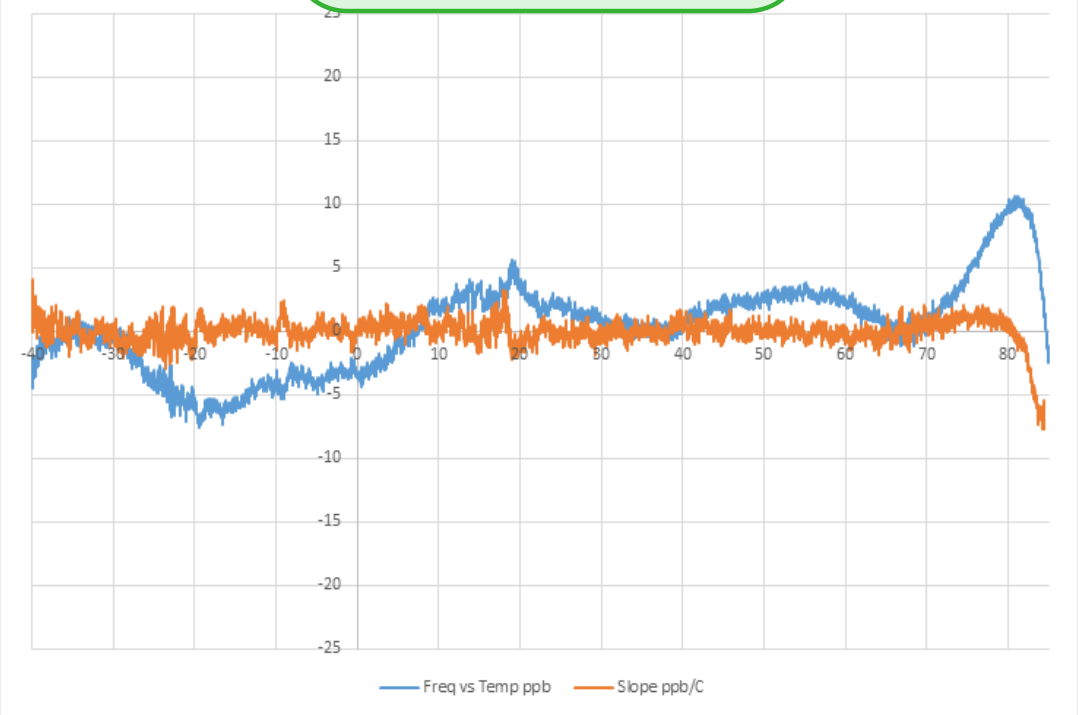


FREQUENCY STABILITY FROM -40°C TO 85°C

Typical TCXO FvsT response



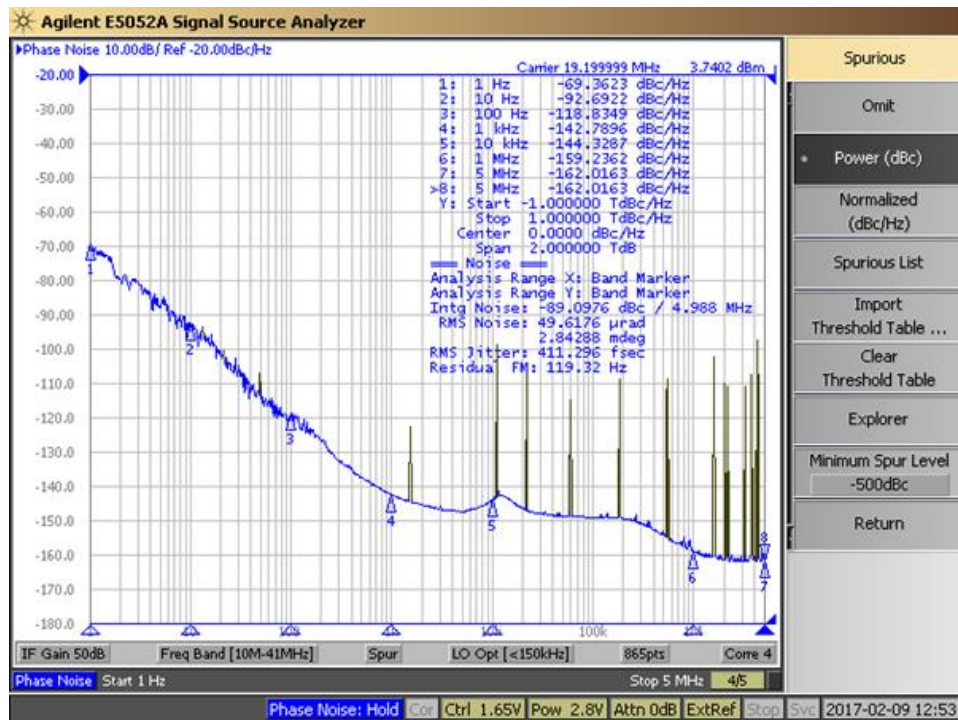
Digital TCXO FvsT response



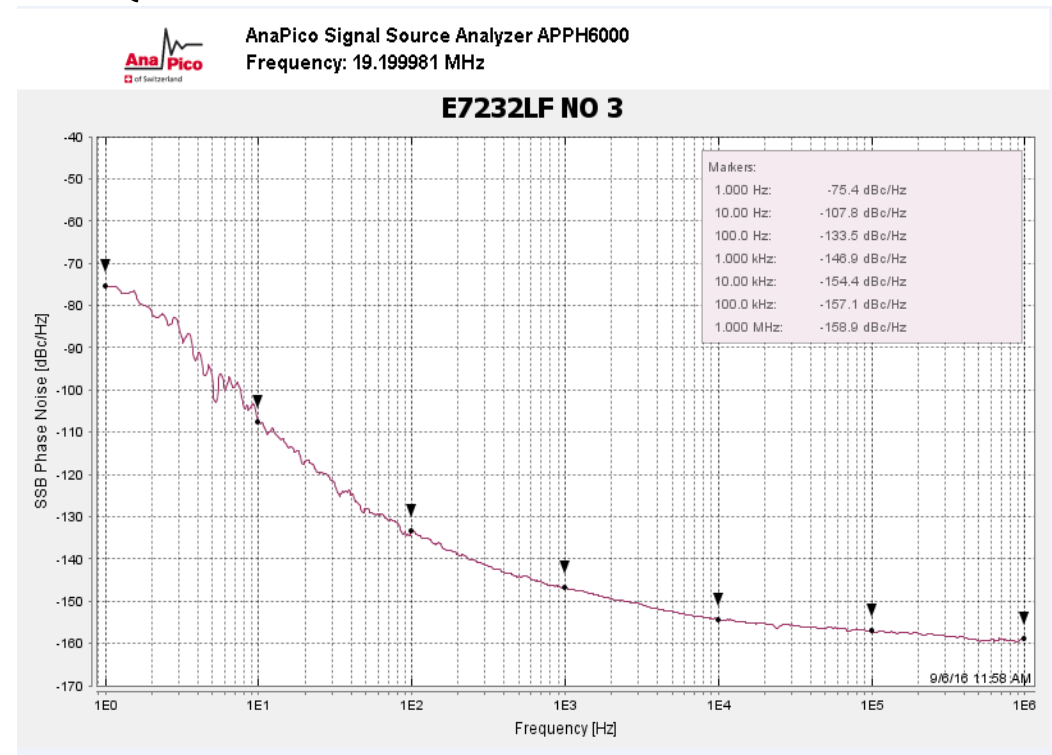
Low Spurious Levels



◀ Other Technologies



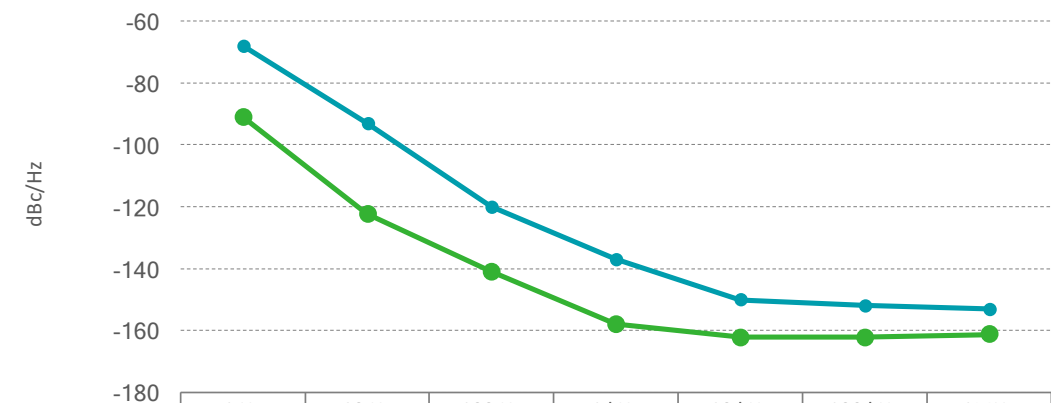
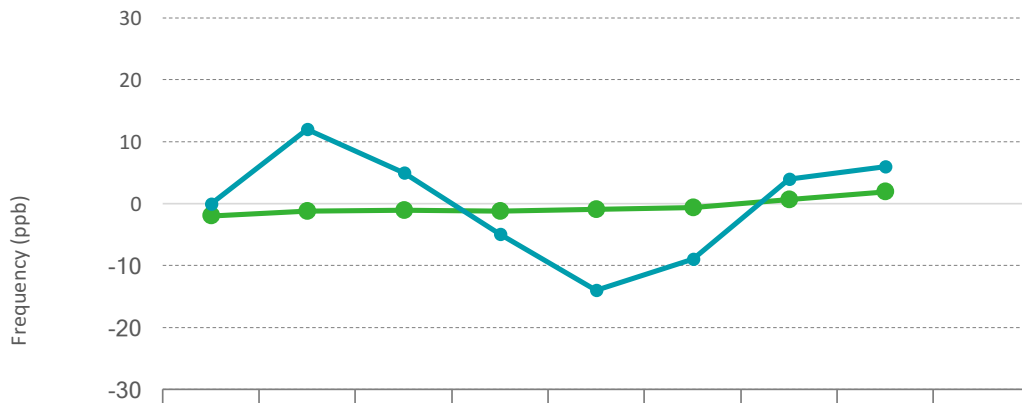
◀ Quartz





Improvements in IC based OCXOs

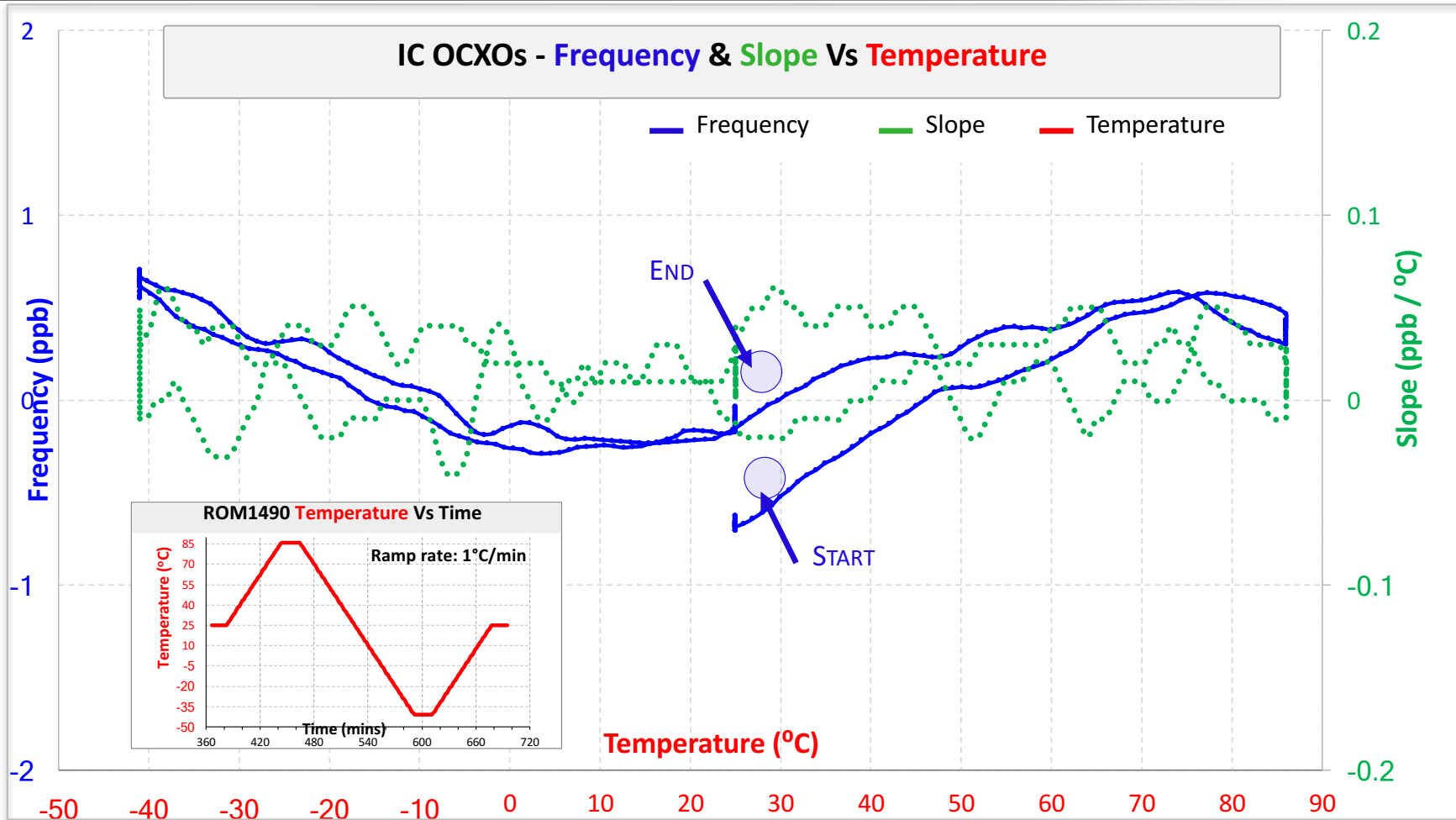
Feature	Previous Generation	Current generation
Temperature Stability	+/-20ppb	+/-5ppb
Ageing	1ppb	0.2ppb
Crystal Type	AT	AT, SC, SC-Strips
Frequency	<50M	100M+
Support for 3OT	No	Yes
Phase Noise (dBc/Hz@Hz, for 10M)		



	-40	-20	0	20	40	60	80	85
Current Gen	-2	-1.2	-1.1	-1.2	-0.9	-0.7	0.7	1.9
Prev Gen	0	12	5	-5	-14	-9	4	6

	1 Hz	10 Hz	100 Hz	1 kHz	10 kHz	100 kHz	1 MHz
Current Gen	-91	-122.4	-140.9	-157.8	-162.1	-162.1	-161.2
Prev Gen	-68	-93	-120	-137	-150	-152	-153

Typical IC based OCXO F vs T performance



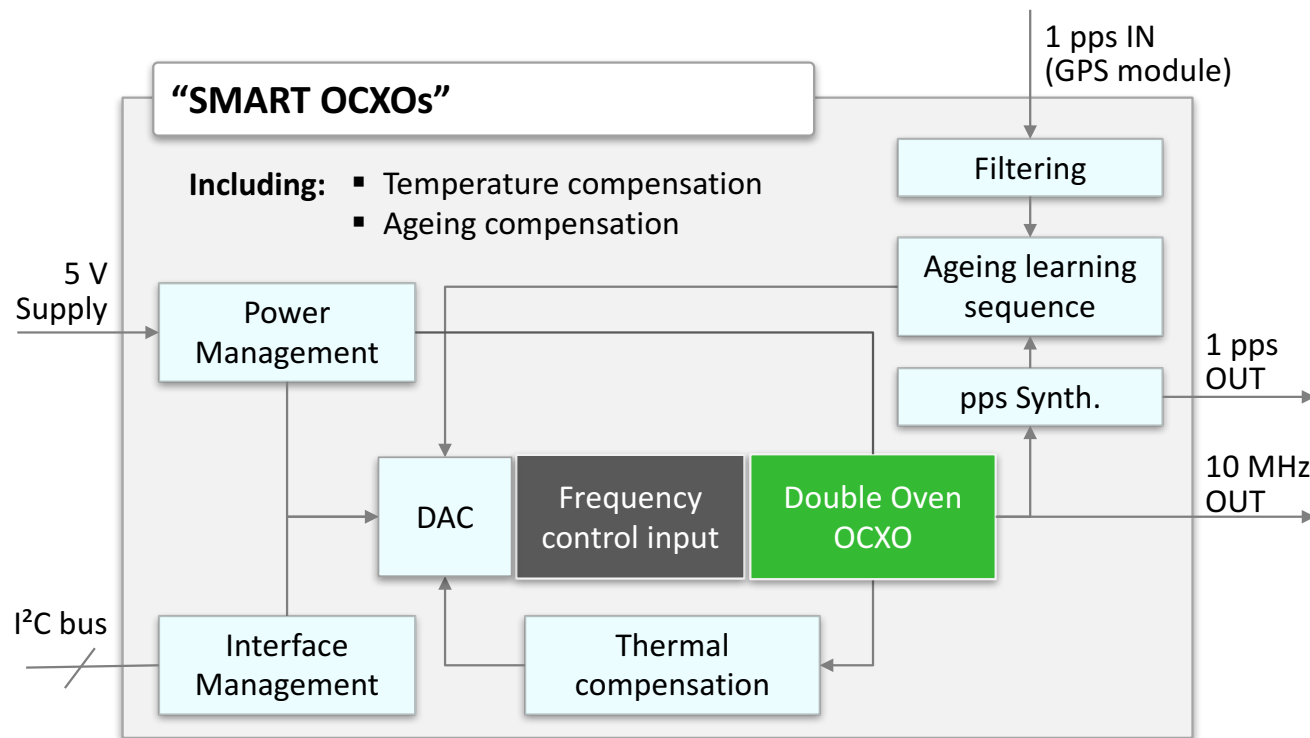
Improvements in Stratum 3E stability levels



Discrete

Package Size	25 x 22 mm
Temperature Stability	10 ppb pk-pk
Ageing	1ppb/day
Life Time Accuracy	±2 ppm
Temperature range	-40 to 85 °C
Sensitivity	0.2 ppb/°C
Hermetic sealing	Yes
Power	0.75 W

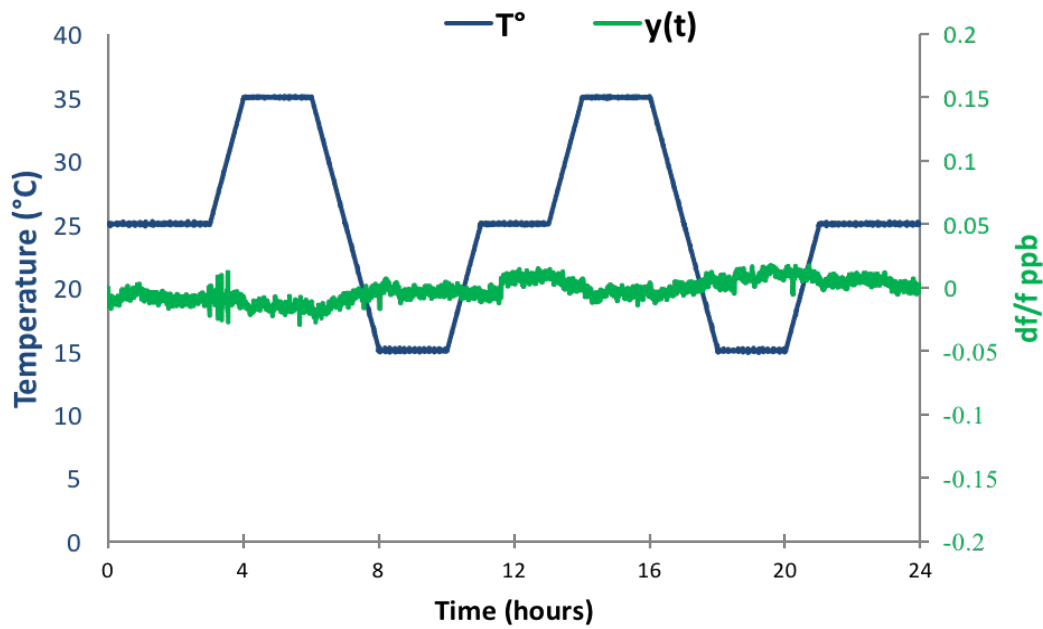
Improvements on long holdover



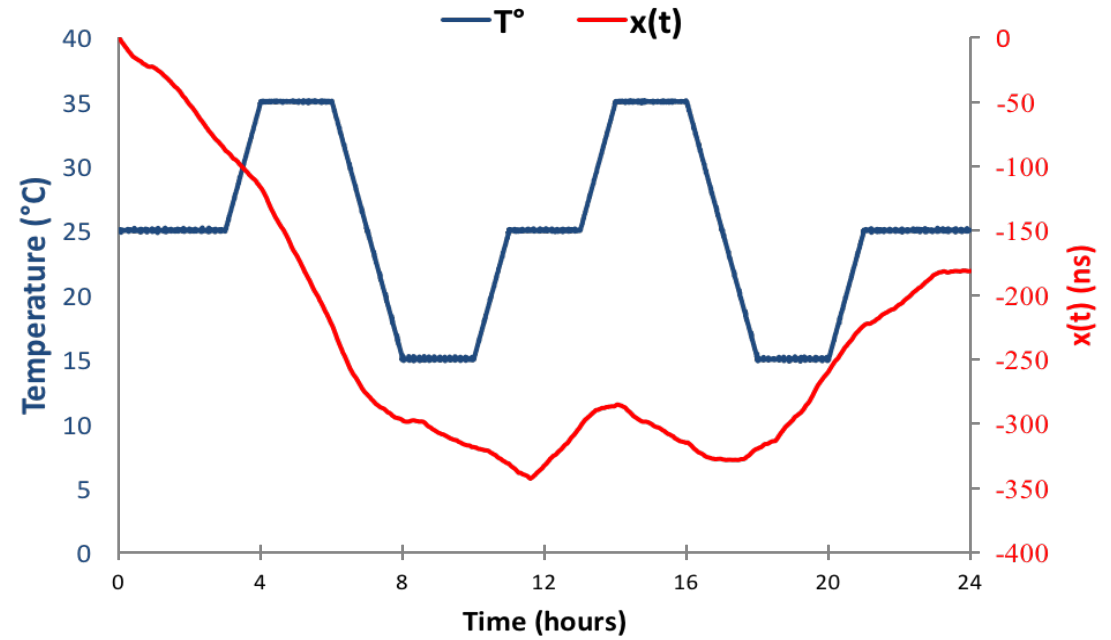
Holdover



ROX5242T1 frequency stability



ROX5242T1 time holdover

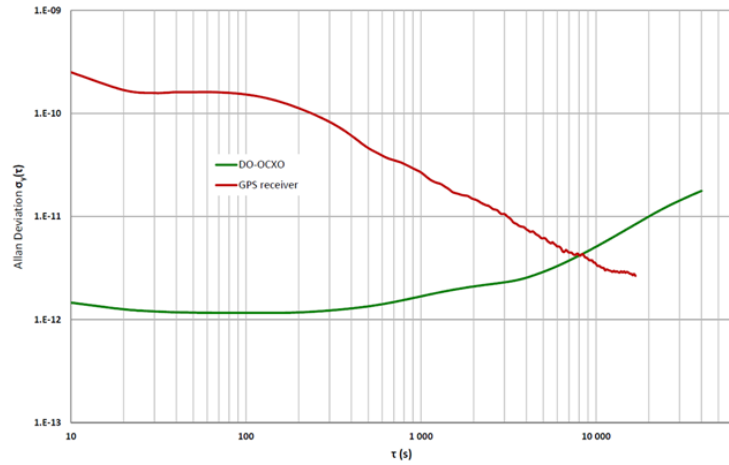


Performance updates

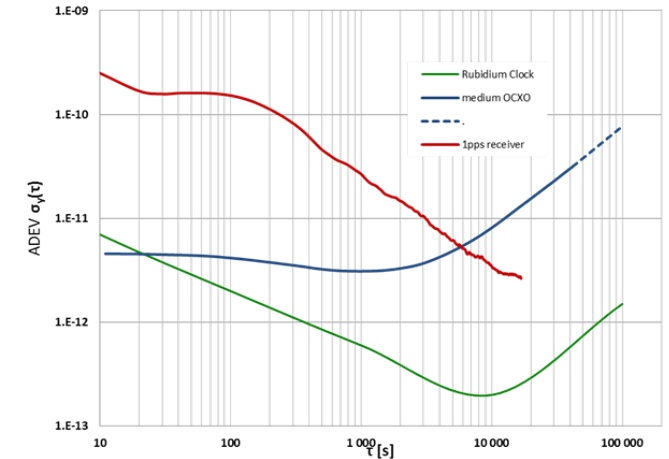


Characteristics	Current D-OCXO	Commercial Rb Clock
Dimension (L x W x H in mm)	38 x 27 x 12	51 x 51 x 18
Power Consumption		
at start	3.5W	14W
steady state @ +25°C	1.5W	5W
Operating Temperature	from -40°C to +85°C	from -10°C to +75°C
Holdover Performance	with 1pps & learning	
Stable conditons	1.5µs for 24h	
including ± 20°C variation	8µs for 24h	7µs for 24h
Frequency Stability	with 1pps & learning	
Vs. Time / Long Term Ageing		
per Day	< 2E-10	< 2.5E-11
Vs. Temperature (peak to peak)	< 1.0E-9	< 0.1E-9
Short term (Allan std. Dev. 1s)	< 3E-12	< 3E-11
COST COMPARISON	x	10x

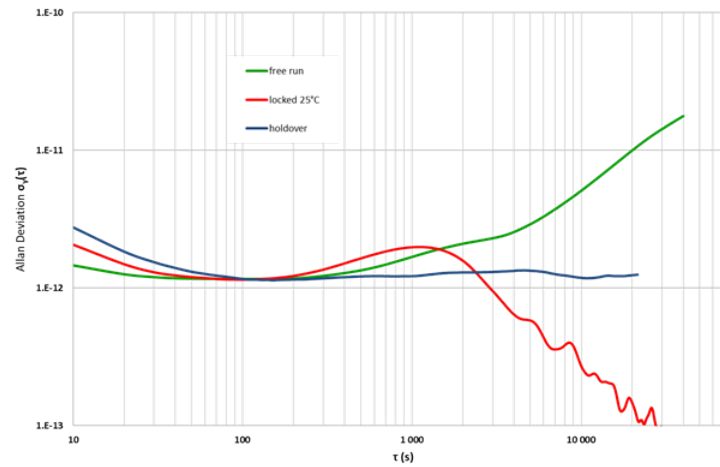
Performances



clock performance -overlapping ADEV



SMART Module -ADEV performance



Summary



- ◀ Quartz based crystal oscillators provide low phase noise, stable clock references
- ◀ Improved technologies move the performance of TCXOs to OCXO levels
- ◀ Strip SC crystal technology improves performance, power & cost in Stratum 3E stability levels
- ◀ IC-based oscillators reduce power and footprint profile at given stability levels
- ◀ SMART OCXOs performances move closer to Rubidium

References & Acknowledgements



- ◀ **W.L. Bond, Crystal Technology, John Wiley & Sons, New York, 1976.**
- ◀ **J. A. Kusters, "Resonator and Device Technology," in E. A. Gerber and A. Ballato, Precision Frequency Control, Vol. 1, pp.161-183, Academic Press, 1985.**

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Thank you

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